



# Product End-of-Life Disassembly Instructions

**Product Category:** Networking Equipment

**Marketing Name / Model**

**[List multiple models if applicable.]**

HP HSR6800 FIP-300 Flex Int Platform Mod(JG671A)

HP HSR6800 FIP-310 Flex Int Platform Mod(JG672A)

Flexible Interface Platform 300,1 HIM Slot,12-Port Gigabit Ethernet Combo

Flexible Interface Platform 310,1 HIM Slot,2-Port 10Gigabit SFP+,4-Port Gigabit Ethernet Combo

Flexible Interface Platform C300,1 HIM Slot,12-Port Gigabit Ethernet Combo

Flexible Interface Platform C310,1 HIM Slot,2-Port 10Gigabit SFP+,4-Port Gigabit Ethernet Combo

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances	0
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## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on the two fake front panels 1, and then remove the two fake front panels 1 from front panel 11. Later, remove the film 8 and shielding fingers 9 from fake front panel 1.
2. Unscrew the screws on pcb 2, sheet metal 3 and heat sink 5, and then remove pcb 2, sheet metal 3 and heat sink 5 from front panel 11.
3. Unscrew guiding set 4, and then remove guiding set 4 from pcb 2.
4. Remove film 6 from front panel 11.
5. Remove film 7 from sheet metal 3.
6. Remove shielding fingers 10 from front panel 11.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

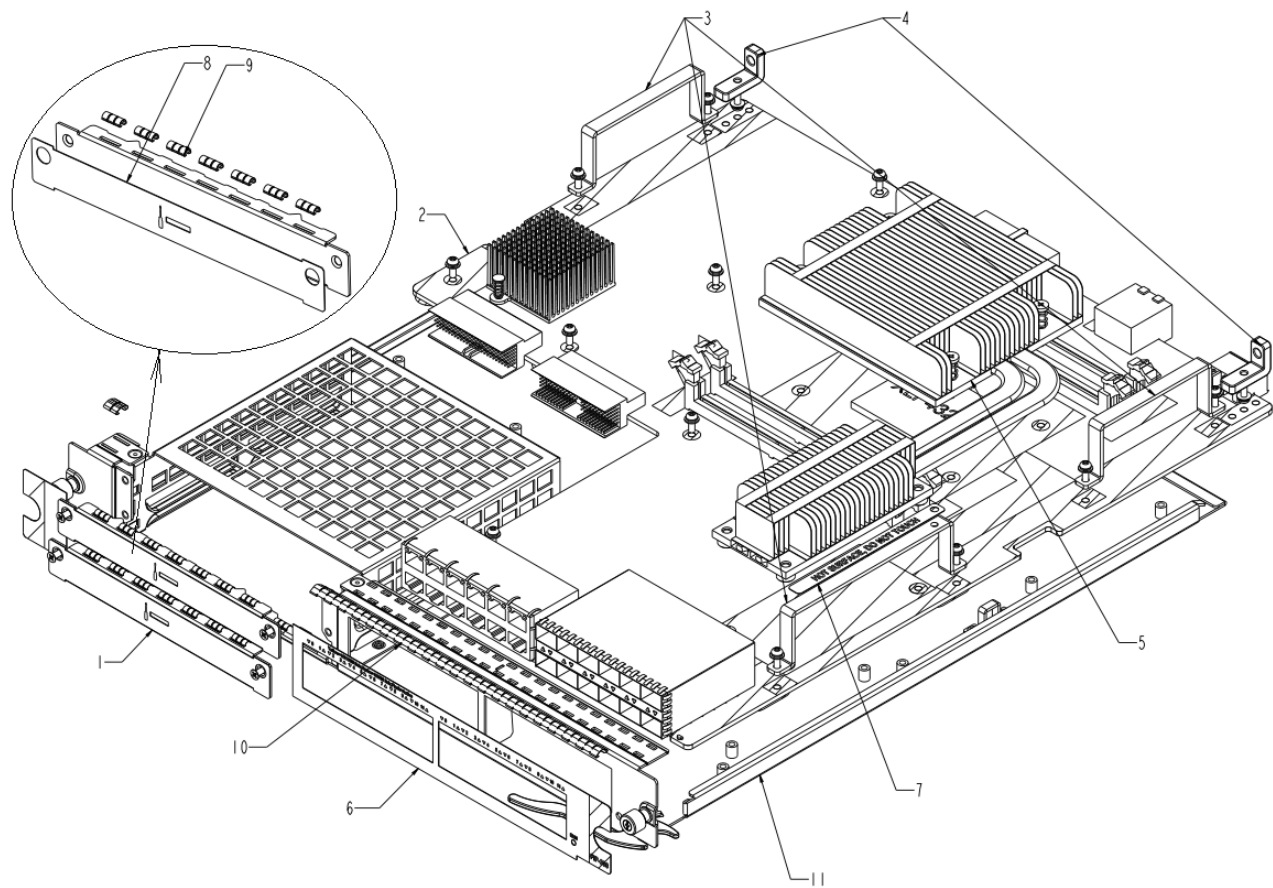


Figure 1

## 3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
	1	Fe	65	1.79%		Fe recycling
	2	Complex PWB	1400	38.46%	The surface If PCB is greater than 10 square centimeters	
	3	Fe	60	1.65%		Fe recycling
	4	Al	9	0.25%		Al recycling
	5	Al	250	6.87%		Al recycling
	6	PC	2	0.05%		Pla recycling
	7	PC	0.2	0.01%		Pla recycling
	8	PC	1.8	0.05%		Pla recycling
	9	Be-Cu	0.5	0.01%		Cu recycling
	10	Be-Cu	1	0.03%		Cu recycling
	11	Fe	1850	50.83%		Fe recycling

#### 4. Revised record

Date	Version	Author	Modify content
2013.08.29	V0	Xiang Yanmin	Initial version
2013.09.02	V1	Xiang Yanmin	"List multiple models if applicable" add 0231A2F9 and 0231A2FA codes
2014.11.19	V2	Huang Jun	"List multiple models if applicable" add 0231A2S8 and 0231A2S9 codes